

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5220673

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YONG LI	12/30/2016
RECEIVING PARTY DATA		
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION	
Street Address:	18 ZHANG JIANG ROAD	
Internal Address:	PUDONG NEW AREA	
City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	201203	
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION	
Street Address:	18 WEN CHANG ROAD, ECONOMICAL-TECHNOLOGICAL	
Internal Address:	DEVELOPMENT AREA, DAXING DISTRICT	
City:	BEIJING	
State/Country:	CHINA	
Postal Code:	100176	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16179291	
CORRESPONDENCE DATA		
Fax Number:	(415)576-0300	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	(415) 576-0200	
Email:	TDIEP@KILPATRICKTOWNSEND.COM	
Correspondent Name:	KILPATRICK TOWNSEND & STOCKTON LLP	
Address Line 1:	1100 PEACHTREE STREET NE	
Address Line 2:	SUITE 2800	
Address Line 4:	ATLANTA, GEORGIA 30309	
ATTORNEY DOCKET NUMBER:	087720-048610US-1112369	

NAME OF SUBMITTER:	THUY DIEP
SIGNATURE:	/ Thuy Diep /
DATE SIGNED:	11/02/2018
Total Attachments: 2 source=Assignment_087720-048610US-1112369#page1.tif source=Assignment_087720-048610US-1112369#page2.tif	

ASSIGNMENT
(Patent Application)

I, the undersigned, have invented certain inventions and improvements disclosed in a utility (provisional or non-provisional) or design patent application entitled

“ESD PROTECTION DEVICE AND METHOD”

the specification of which is provided with this Assignment and identified by the Attorney Docket No. above.

For one dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which I acknowledge, I:

Agree to assign, transfer, convey, and sell, hereby assign, transfer, convey, and sell and have assigned, transferred, conveyed, and sold to **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, having a principal place of business at 18 Zhang Jiang Road, Pudong New Area, Shanghai, People's Republic of China 201203 *and* **Semiconductor Manufacturing International (Beijing) Corporation**, a corporation of People's Republic of China, having a principal place of business at 18 Wen Chang Road, Economical-Technological Development Area, Daxing District, Beijing, 100176, People's Republic of China, the entire right, title, and interest in and to:

- (a) all intellectual property (including, without limitation, any innovation, information, invention, discovery, product, process, work or design) disclosed, embodied, shown, or claimed in the above-referenced patent application, implicitly or explicitly;
- (b) the above-referenced patent application, the right to claim priority to the above-referenced patent application, all applications based in whole or in part upon the above-referenced patent application, including, without limitation, all applications that are a provisional, non-provisional, design, divisional, continuation, continuation-in-part, registration, utility model, industrial design, reissue, renewal, substitute, extension, reexamination, post-grant review, inter partes review, supplemental examination or non-U.S. patent application or application for other rights based in whole or in part on the above-referenced patent application;
- (c) all patents (including, without limitation, all U.S. and non-U.S. patents, registrations, utility models, industrial designs, design patents, counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued

ASSIGNMENT

ESD PROTECTION DEVICE AND METHOD

Attorney Docket No.: 087720-048600US-1015254

Page 2 of 2

upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

(d) all claims for damages by reason of past infringement of any rights under the applications or patents described in (a), (b) or (c) of this paragraph (including provisional rights to reasonable royalties pursuant to 35 U.S.C. §154(d)) and the right to sue for and collect such damages and royalties for Assignees' own use.

2. Authorize and request the U.S. Patent and Trademark Office or any other U.S. or non-U.S. agency to issue to the Assignees any and all patent(s), or other rights or documents, resulting from the intellectual property, patent application(s) and patents described in paragraph 1 of this Assignment.
3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignees' expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignees, its successors, assigns and other legal representative, and shall be binding upon me, as well as my heirs, legal representatives, and assigns.
5. Promise and affirm that I have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.
6. Authorize Kilpatrick Townsend & Stockton to insert above the application number and filing date of the above-described patent application when known.

Signed on the dates indicated beside my signature.

Signature: 李勇 / Yong Li
YONG LI

Date: 2016-12-30

69013444v1